

RF Low Noise FET CE3521M4

20 GHz Low Noise FET in Dual Mold Plastic PKG

DESCRIPTION

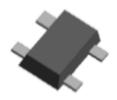
- Low Noise and High Gain
- Original Dual Mold Plastic package

FEATURES

Low noise figure and high associated gain:
 NF = 0.70 dB TYP., Ga = 11.9 dB TYP.
 @V_{DS} = 2 V, I_D = 10 mA, f = 20 GHz

PACKAGE

Flat-lead 4-pin thin-type super minimold package



APPLICATIONS

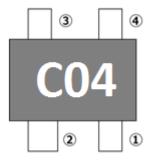
- DBS LNB gain-stage, Mix-stage
- Low noise amplifier for microwave communication systems

ORDERING INFORMATION

| Part Number | Order Number | Package | Marking | Description |
|-------------|--------------|-----------------|---------|---|
| CE3521M4 | CE3521M4-C2 | Flat-lead 4-pin | C04 | Embossed tape 8 mm wide |
| | | thin-type super | | Pin 1 (source), Pin 2 (drain) |
| | | minimold | | face the perforation side of |
| | | package | | the tape |
| | | | | MOQ 15 kpcs/reel |



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



| Pin No. | Pin Name |
|---------|----------|
| 1 | Source |
| 2 | Drain |
| 3 | Source |
| 4 | Gate |

ABSOLUTE MAXIMUM RATINGS

(TA = +25°C, unless otherwise specified)

| (1A = +25 C, unless otherwise specified) | | | |
|--|------------------|-----------------------------|------|
| Parameter | Symbol | Rating | Unit |
| Drain to Source Voltage | V_{DS} | 4.0 | V |
| Gate to Source Voltage | V_{GS} | -3.0 | V |
| Drain Current | I _D | I _{DSS} | mA |
| Gate Current | I_{G} | 80 | μA |
| Total Power Dissipation | P _{tot} | 125 | mW |
| Channel Temperature | T _{ch} | +150 | °C |
| Storage Temperature | T _{stg} | -55 to +125 | °C |
| Operation Temperature | T _{op} | -55 to +125 ^{Note} | °C |

Note Refer to Total Power Dissipation vs. Ambient Temperature graph on page 4

RECOMMENDED OPERATING RANGE

 $(TA = +25^{\circ}C. \text{ unless otherwise specified})$

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|-------------------------|-----------------|------|------|------|------|
| Drain to Source Voltage | V _{DS} | +1 | +2 | +3 | V |
| Drain Current | I _D | 5 | 10 | 15 | mA |



ELECTRICAL CHARACTERISTICS

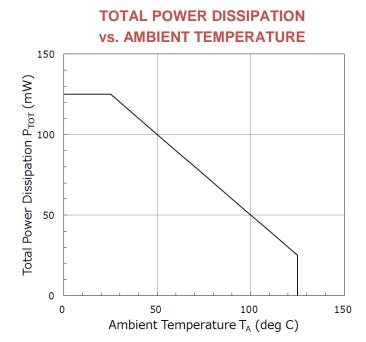
(TA = +25°C, unless otherwise specified)

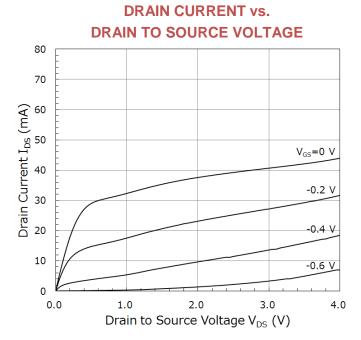
| Parameter | Symbol | Condition | MIN. | TYP. | MAX. | Unit |
|--------------------------------|------------------|----------------------------------|-------|-------|-------|------|
| Gate to Source Leak Current | I _{GSO} | V _{GS} = -3.0V | - | 0.4 | 10 | μΑ |
| Saturated Drain Current | I _{DSS} | $V_{DS} = 2V$, $V_{GS} = 0V$ | 23 | 40 | 57 | mA |
| Gate to Source Cut-off Voltage | $V_{GS(off)}$ | $V_{DS} = 2V, I_{D} = 100 \mu A$ | -1.10 | -0.75 | -0.39 | V |
| Transconductance | Gm | $V_{DS} = 2V$, $I_D = 10mA$ | 47 | 62 | - | mS |
| Noise Figure | NF | $V_{DS} = 2V, I_{D} = 10mA,$ | - | 0.70 | 1.05 | dB |
| Associated Gain | Ga | f = 20GHz | 9.9 | 11.9 | - | dB |

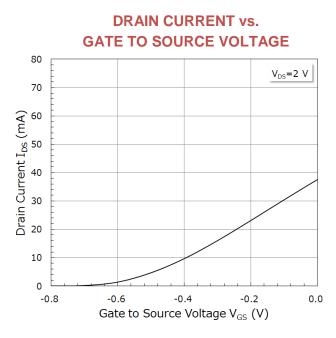


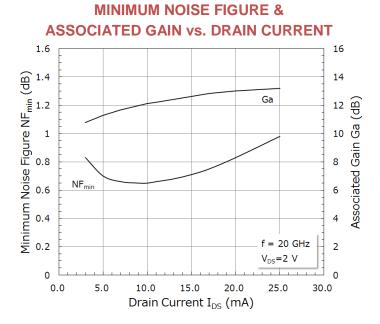
TYPICAL CHARACTERISTICS:

(TA=+25°C, unless otherwise specified)











S-PARAMETERS

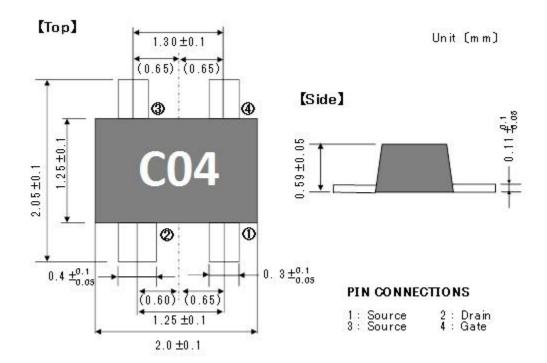
S-Parameters are available on the CEL web site.

RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are provided on the CEL web site.

PACKAGE DIMENSIONS

Flat-lead 4-pin thin-type super minimold package





REVISION HISTORY

| Version | Change to current version | Page(s) |
|-----------------------|---|---------|
| CDS-0020-03 (Issue A) | Initial datasheet | N/A |
| February 19, 2016 | | |
| CDS-0020-03 (Issue B) | Updated Marking Information | 1, 2, 3 |
| April 27, 2016 | | |
| CDS-0020-04 (Issue A) | Updated Specs in "Absolute Maximum Ratings" Table | 2, 4, 5 |
| July 29, 2016 | Added "Typical Characteristics" section (graphs) | |
| | Added "S-Parameters" and "Recommended Soldering | |
| | Conditions" sections | |



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[CAUTION]

This product uses gallium arsenide (GaAs) of the toxic substance appointed in laws and ordinances. GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not dispose in fire or break up this product.
- Do not chemically make gas or powder with this product.
- When discarding this product, please obey the laws of your country.
- Do not lick the product or in any way allow it to enter the mouth.

[CAUTION]

Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

CEL Headquarters • 4590 Patrick Henry Drive • Santa Clara, CA 95054 • Tel: (408) 919-2500 • www.cel.com

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